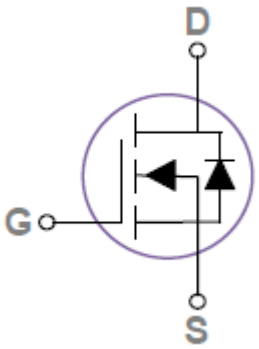
SPN8632
N-Channel Enhancement Mode MOSFET

DESCRIPTION
The SPN8632 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.
This high density process is especially tailored to minimize on-state resistance.
These devices are particularly suited for low voltage application , notebook computer power management and other battery powered circuits where high-side switching .

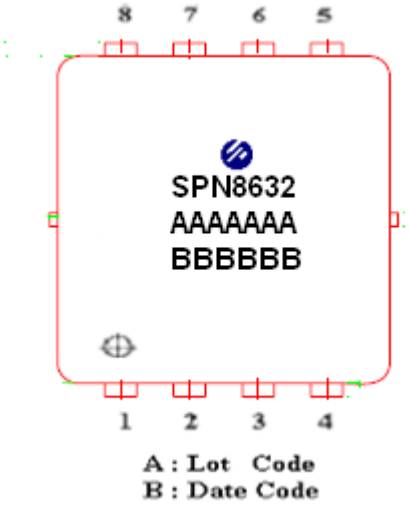
APPLICATIONS
- MB/VGA/Vcore
- POL Applications
- SMPS 2nd SR

FEATURES
- 30V/12A,$R_{DS(ON)}$=4.2mΩ@V_{GS}=10V
- 30V/6A,$R_{DS(ON)}$=6mΩ@V_{GS}=4.5V
- Super high density cell design for extremely low R_{DS} (ON)
- Exceptional on-resistance and maximum DC current capability
- PPAK3x3 package design

PIN CONFIGURATION(PPAK3x3-8L)



PART MARKING



SPN8632
N-Channel Enhancement Mode MOSFET

PIN DESCRIPTION

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN8632DN8RGB	PPAK3x3-8L	SPN8632

※ SPN8632DN8RGB : 13" Tape Reel ; Pb – Free; Halogen - Free

ABSOULTE MAXIMUM RATINGS

(T_A=25℃ Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V_{DSS}	30	V
Gate –Source Voltage		V_{GSS}	±20	V
Continuous Drain Current(T_J=150℃)	T_A=25℃	I_D	12	A
	T_A=100℃		8.5	
Pulsed Drain Current		I_{DM}	120	A
Continuous Source Current(Diode Conduction)		I_S	30	A
Power Dissipation	T_A=25℃	P_D	7	W
Operating Junction Temperature		T_J	-55/150	℃
Storage Temperature Range		T_{STG}	-55/150	℃
Thermal Resistance-Junction to Ambient		$R_{\theta JA}$	62	℃/W

ELECTRICAL CHARACTERISTICS

(T_A=25℃ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V , I_D =250uA	30			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS},I_{DS} =250uA	1.2	1.6	2.5	
Gate Leakage Current	I_{GSS}	V_{DS} = 0V,V_{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 30V,V_{GS}=0V, T_J = 25℃			1	uA
		V_{DS} = 24V,V_{GS}=0V, T_J = 125℃			10	
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS} = 10V, I_D=12A		3.8	4.2	mΩ
		V_{GS} = 4.5V, I_D=6A		5.2	6	
Forward Transconductance	gfs	V_{DS}=10V, I_D=6A		12		S
Diode Forward Voltage	V_{SD}	I_F = 1A,V_{GS} = 0V			1	V
Dynamic						
Total Gate Charge	Q_g	V_{DS} = 15V,V_{GS} = 4.5V, I_D =12A		24	34	nC
Gate-Source Charge	Q_{gs}			4.2	6	
Gate-Drain Charge	Q_{gd}			13	18	
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 25V, F=1MHz		2200	3190	pF
Output Capacitance	C_{oss}			280	405	
Reverse Transfer Capacitance	C_{rss}			177	255	
Turn-On Time	$t_{d(on)}$	(V_{DD} = 15V,I_D = 15A, V_{GEN}=10V,R_G = 3.3Ω)		12.6	24	ns
	t_r			19.5	37	
Turn-Off Time	$t_{d(off)}$			42.8	81	
	t_f			13.2	25	

TYPICAL CHARACTERISTICS

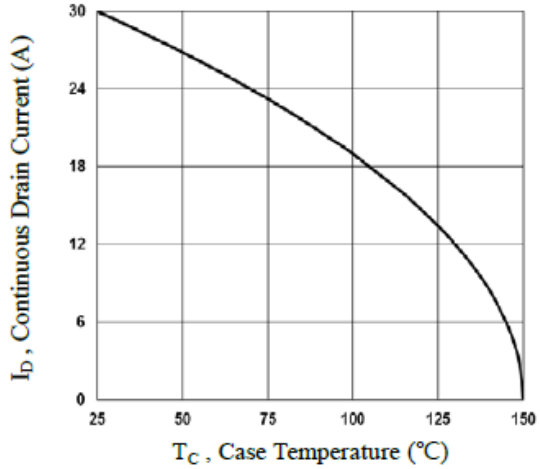


Fig.1 Continuous Drain Current vs. T_c

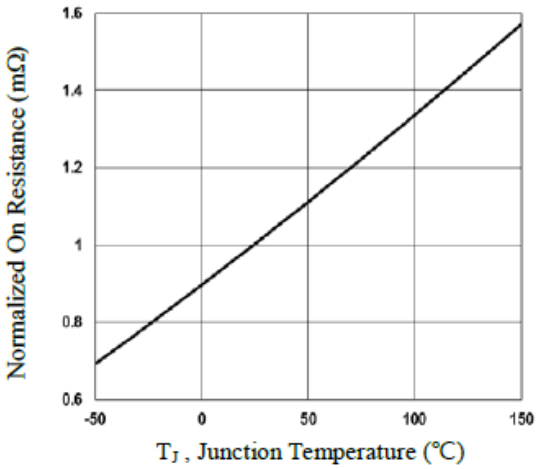


Fig.2 Normalized RDSON vs. T_J

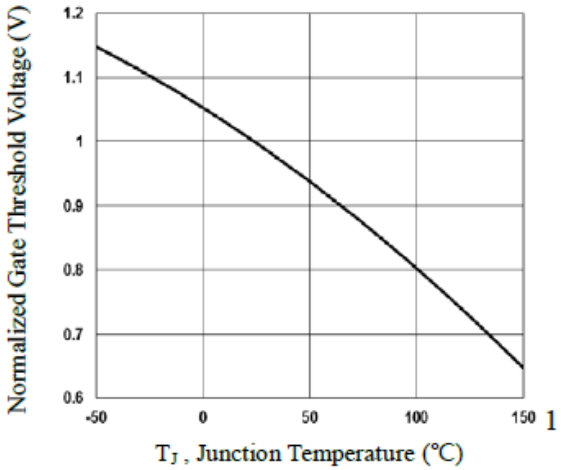


Fig.3 Normalized V_{th} vs. T_J

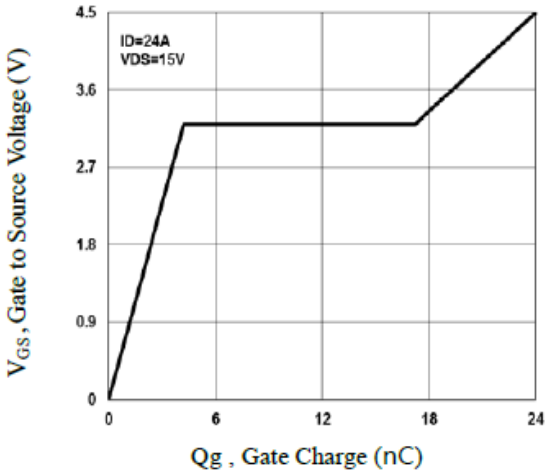


Fig.4 Gate Charge Waveform

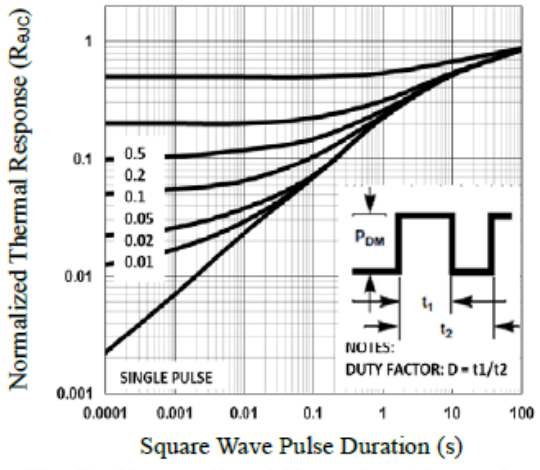


Fig.5 Normalized Transient Impedance

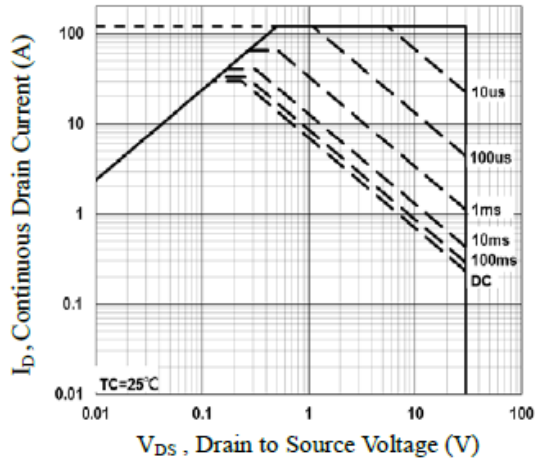


Fig.6 Maximum Safe Operation Area

TYPICAL CHARACTERISTICS

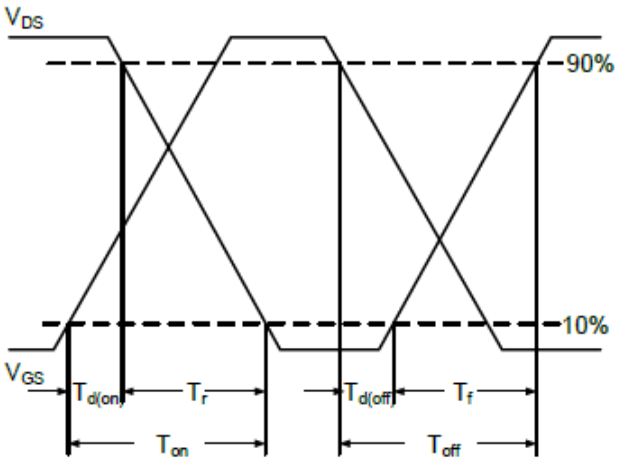


Fig.7 Switching Time Waveform

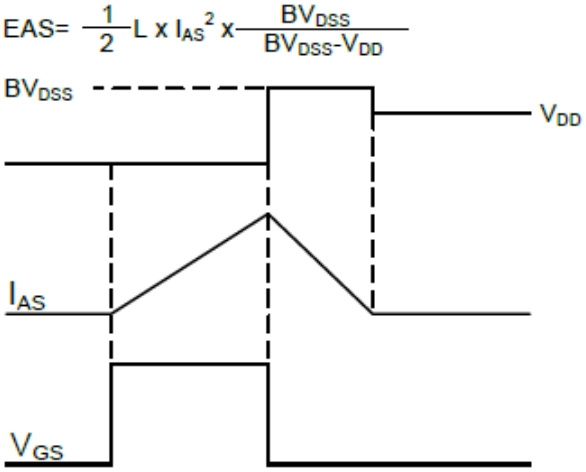
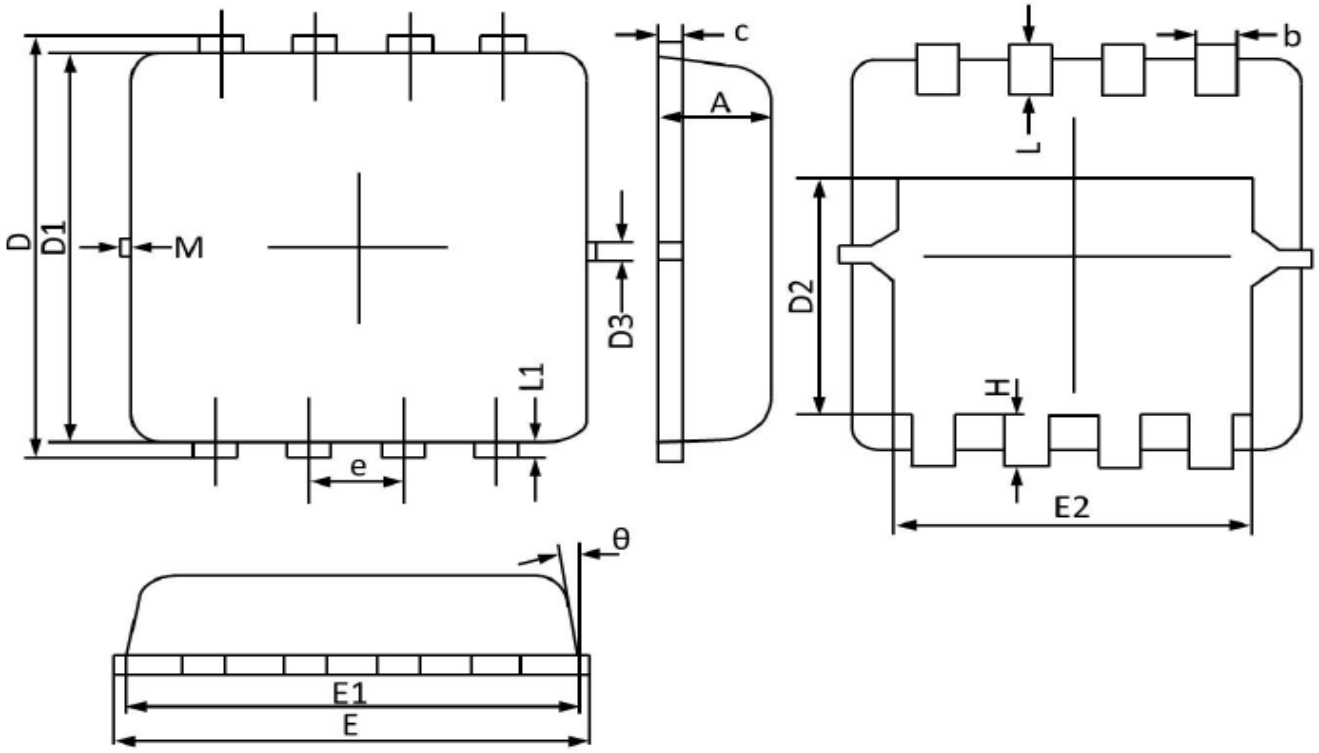


Fig.8 EAS Waveform

PPAK3x3-8L PACKAGE OUTLINE



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	

SYNC Power Corporation
7F-2, No.3-1, Park Street
NanKang District (NKSP), Taipei, Taiwan 115
Phone: 886-2-2655-8178
Fax: 886-2-2655-8468
© http://www.syncpower.com